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Lin et al.

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[54] **EQUIPMENT AND METHOD FOR APPLYING A LIQUID LAYER**

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[75] Inventors: **Ting-Hwang Lin**, Shin Chu;
Shih-Ming Wang, Kaohsiung;
Li-Chum Chen, Hsin-chu, all of
Taiwan

Primary Examiner—Janyce Bell

[73] Assignee: **Taiwan Semiconductor
Manufacturing Company, Ltd.**,
Hsin-Chu, Taiwan

Attorney, Agent, or Firm—George O. Saile

[57] **ABSTRACT**

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A method and apparatus for applying a liquid to the surface of semiconductor wafer are described. The wafer is rotated about an axis; perpendicular to its main surface. Liquid is dispensed onto the surface of the spinning wafer from at least two dispensing bottles. One of the dispensing bottles is positioned above the center of rotation while the others are located between it and the wafer's edge. The rate at which liquid emerges from each of the dispensing bottles is independently controlled for each bottle.

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427/385.5; 437/231; 437/235; 437/245

[58] Field of Search 427/240, 96, 126.2,
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118/52

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16 Claims, 3 Drawing Sheets

